

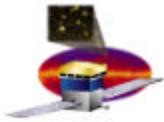
# GLAST Large Area Telescope Calorimeter Subsystem

## 5.1 Dual PIN Photodiode

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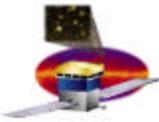


# DPD Outline

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- ❑ Goals and History
- ❑ Responsibilities and Status
- ❑ Requirements
- ❑ Changes from EM to FM
  - **Highlight: Optical Window**
- ❑ Qualification Program
- ❑ Procurement
- ❑ Schedule

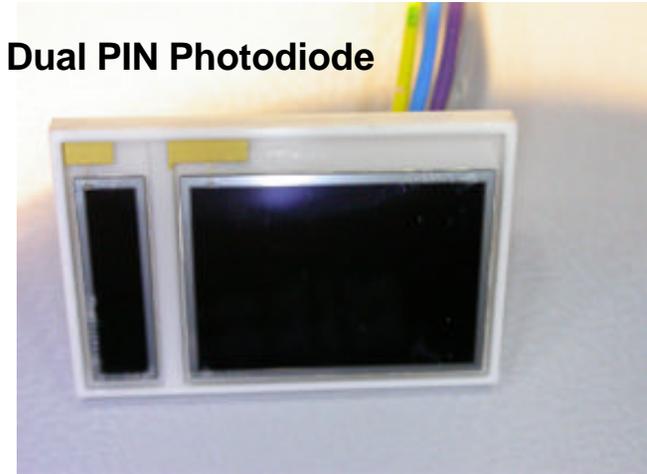




# Goals and History

- Requirements on DPD are linked to the performance of the CDE and ultimately CAL
  - Collects the light from energy depositions in the Csl (SIGNAL)
  - DPD electrical characteristics (capacitance and dark current) affect the front end electronics NOISE
  - Desire is to maximize SIGNAL/NOISE

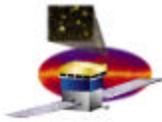
CAL EM Dual PIN Photodiode



## 7 years of DPD development

	PIN Diode	Dates	Optical Window Material	Silicon Die thickness (um)	PIN A Area (mm <sup>2</sup> )	PIN B Area (mm <sup>2</sup> )
NASA ATD Program	S3590	1/1996 – 12/1998	Hard epoxy resin		n/a	100
	S3590-08 SPL	2/1999 – 10/2001	Hard epoxy resin	200	24	96
EM DPD	S8576	1/2001 -	Hard epoxy resin	300	25	152
Flight DPD	S8576-01	2/2003 -	Silicone resin	300	25	147



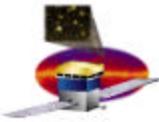


# Responsibilities and Status

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- **FM Requirements and Specs – joint responsibility of NRL and CEA**
  - Worked closely with Hamamatsu in USA and Japan
- **FM Procurement – joint responsibility of NRL and CEA.**
  - **CEA contributions**
    - qualification and acceptance screening of all DPD
    - procurement of ~\$200K (USD) in flight diodes
  - **NRL contributions**
    - overall management of the effort,
    - coordination and negotiation of the specification, and
    - procurement of the residual flight diodes (~\$400K)
- **FM Status**
  - Specification is complete: **LAT-DS-00209-12**
  - Successful Procurement Readiness Review: **13 Feb 03**
  - Qualification program will begin June 03
    - Evaluation of pre-production FM DPDs in progress now



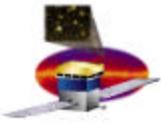


# DPD Requirements

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- **CAL Flight Dual PIN Photodiode Specification, LAT-DS-00209-12**
  - **Electrical and Optical Requirements**
    - **Area, sensitivity, dark current, capacitance, bias voltage**
  - **Ceramic Carrier Requirements – mechanical**
    - **Dimensions and tolerance control, electrical leads**
  - **Manufacturing Requirements**
    - **Die attach, wire bonds, optical window encapsulant**
  - **Product Assurance Requirements – Qualification and screening**
  - **Environmental Requirements**
  - **Deliverables – Documentation and data package**
  - **Shipping and handling**
  - **Acceptance Criteria**
- **Crystal Detector Element Specification, LAT-SS-01133-02**
  - **DPD bonding to Csl**
  - **Electrical lead treatment and positioning**





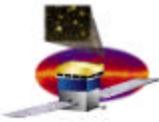
# Changes from EM to Flight DPD

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- **Several changes have been made based on EM lessons**
  - Ceramic carrier size: S8576-01 carrier is 1 mm smaller in width and length
  - PIN B silicon die active area: S8576-01 die is 0.5 mm smaller in one dimension (~3%)
  - Electrical lead positions have been moved
  - Electrical leads shall be tinned by Hamamatsu prior to assembly of the silicon die to the carrier
  - **Optical window encapsulant is changed to Shin Etsu KJR 9022E silicone resin**
  - Shipping container has been modified to provide ESD protection and to protect the electrical leads from bending

Let's talk about  
this one

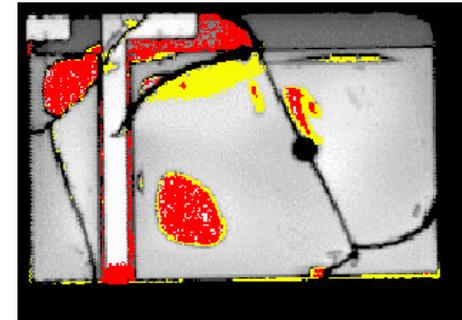




# Optical Window Issues

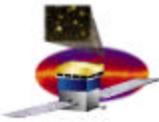
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- **The problem with EM**
  - **Hard epoxy window of EM S8576 could not withstand thermal cycling (-30C to +50C, 100 cycles)**
    - **Extensive testing program in France and US**
      - ~650 units used in bonding, thermal, optical, etc. studies
      - **“Microcracks”, severe cracks, delamination**
        - Latter two could cause electrical failure
  - **But otherwise it worked well**
    - **Bonds to crystal were excellent and exceeded specs**
      - Mechanical strong
      - Thermally stable
      - Optically clear
- **The solution for FM**
  - **Make the window flexible: ShinEtsu silicone**



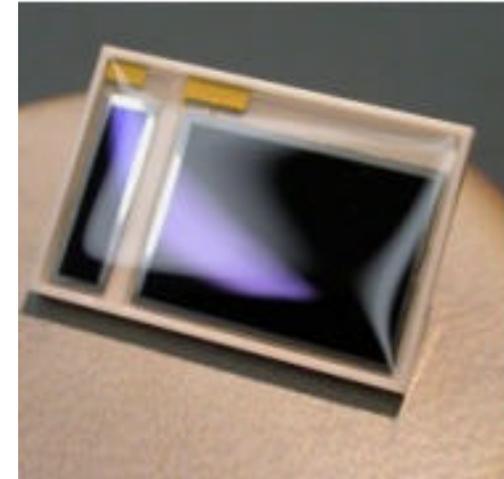
Acoustic microscopy  
of failed window

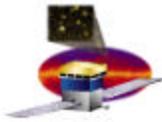




# Optical Window Verification

- **Verification program for ShinEtsu window**
  - Report LAT-TD-1476-01
  - Tested performance of commercial PDs and sample EM DPDs with ShinEtsu window
    - **Thermal stability of window**
      - No cracks or delam at up to 180 cycles
    - **Out-gassing**
      - After bake-out, passes Mass Loss and Condensible Volatiles requirements
    - **Bond compatibility**
      - Forms fully-cured, strong bonds with optical adhesive for CsI(Tl)
    - **Optical properties**
      - Light yield: ~90% of hard epoxy
      - Thermal stability of optical bond: No significant loss of light after >100 cycles
    - **Mechanical strength of bond**
      - Tensile strength: >160 N (spec is >10 N)
      - Shear strength: >0.80 N/mm<sup>2</sup> (spec is >0.12 N/mm<sup>2</sup>)
  - **Conclusion: DPD with ShinEtsu silicone window still exceeds specs**



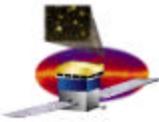


# Qualification Program

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- **Qualification program for FM DPDs is responsibility of CEA**
  - **Begins June 03**
  - **Discussed in agenda item 5.3**
  - **Principle tests**
    - **Solderability of leads**
    - **Moisture uptake**
      - **ShinEtsu window**
    - **Thermal cycling**
      - **stability of ShinEtsu window**
    - **Operating lifetime**
    - **Radiation hardness**
  - **Tests of pre-production samples are in progress now**
  - **Expect no issues**



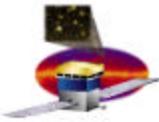


# Procurement Quantities

Level	Operation or Loss Process	Loss %	Loss Count	TOTAL CNT
<b>CDE</b>	<b>Required CDE for Flight</b>			<b>1728</b>
	Flight Spares	6.4%	110	1838
	<b>CEA Delivery to NRL</b>			<b>1838</b>
	Acceptance Test Failures	1.0%	19	1857
<b>DPD</b>	<b>DPD for CDE Acceptance Test</b>			<b>3714</b>
	Bonding Process Fallout	10.0%	413	4127
	PhotoDiode Assy Fallout	2.0%	84	4211
	Solder/Stake Failures	1.0%	43	4254
	Spare DPD	2.0%	87	4341
	Electrical Screening Fallout	1.0%	44	4385
	Dimensional Fallout	1.0%	44	4429
	Lot Acceptance Test	1.0%	45	4474
	DPD Qualification		60	4534
	DPD Evaluation		48	4582
	Bonding Process Development		100	4682
	<b>TOTAL DPD Requirement</b>			<b>4682</b>

Deliveries in quantities of 600 DPD





# Schedule

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- ❑ **First flight deliveries needed June 2003. Hamamatsu requires 3.5 months to manufacture.**
  - **First two months of manufacturing are for fabrication of the ceramic carriers. Assembly and test of the DPD are the remaining time.**
- ❑ **Deliveries are based on 600 diodes at 5 week intervals for the first four deliveries and 3 week intervals for the remaining four deliveries**

